इलेक्ट्रॉनिकी एवं
सूचना प्रौद्योगिकी मंत्रालय
MINISTRY OF
ELECTRONICS AND
INFORMATION TECHNOLOGY
सत्यमेव जयते

इंडिया सेमीकंडक्टर मिशन
India Semiconductor Mission
Catalyzing India's Semiconductor Ecosystem

Digital India
Power To Empower

Agenda : SemiconIndia 2024

Day 1 | Wednesday, 11 Sept 2024		
Time (Hrs)	**Session Name & Description**	**Participants/Speakers**
10:25 AM - 10:30 AM	**Hon’ble Prime Minister arrives at IEML Noida**	
10:30 AM - 10:50 AM	Exhibition inauguration and tour by Hon’ble PM	Global Semiconductors and Electronics Companies
10:50 AM - 10:55 AM	**Hon’ble Prime Minister Arrives at Inauguration Hall**	
10:55 AM - 10:56 AM	**Memento presentation to Hon'ble PM by Hon’ble MEIT**	
10:56 AM - 11:00 AM	**Semicon India Video**	
11:00 AM - 11:05 AM	**Welcome Address by Hon’ble MEIT Shri Ashwini Vaishnaw**	
11:05 AM - 11:25 AM	**Address by leaders from Industry**	**CEOs of Global Semiconductor Companies**
11:25 AM - 11:30 AM	**Address by Hon’ble Chief Minister of Uttar Pradesh**	
11:30 AM - 12:00 AM	**Address by Hon’ble PM**	
	Hon’ble Prime Minister Departs	
13:30 PM - 14:30 PM	**Lunch**	
Session 1: Smart Manufacturing - Building India’s AI-Driven Autonomous Factory of the Future | Hall 2 - Room 2 [Level 2]		
13:30 - 13:35	Welcome Remarks by Session Chair	Mark da Silva, Ph.D., Sr. Director, Smart Manufacturing Initiative - SEMI Smart Manufacturing / Advanced Packaging & Heterogeneous Integration (APHI) Community, SEMI
13:35 - 13:50	Evolution of Smart Manufacturing: Lessons for India’s Leap Ahead to Advanced Factory Automation	Scott Rothenberg, Managing Director, Automation Products Group, Applied Materials, Inc.
13:50 - 14:05	Pioneering AI Enabled Fab	Utpal Shah, Senior Vice President - Strategy and Business Development, Tata Electronics
14:05 - 14:20	Unleashing Power of Advanced Packaging with Smart Manufacturing	Gokul Kumar, Senior Director, Micron Technology,Inc.
14:20 - 14:35	Chips Making Chips: How Virtualization, Digital Twins and Machine Learning are Accelerating the Spiral of Innovation	Dr. David M. Fried, Corporate Vice President of Semiverse™ Solutions, Lam Research
14:35 - 14:50	AI Driven Digital Twins for Semiconductor Manufacturing FABS	Prith Banerjee, Chief Technology Officer, ANSYS
14:50 - 14:55	Closing Remarks by Session Chair	Mark da Silva, Ph.D., Sr. Director, Smart Manufacturing Initiative - SEMI Smart Manufacturing / Advanced Packaging & Heterogeneous Integration (APHI) Community, SEMI

Time (Hrs)	Session Name & Description	Participants/Speakers
Session 2: Workshop on Development of Indigenous Wireless Module | Hall 2 - Room 4 [Level 2]		
15:00 - 15:05	**Opening Remarks** Sh. Akash Tripathi, CEO, India Semiconductor Mission	Welcome Attendees and Introduction to Workshop
15:05 - 15:10	**Address** Sh. S. Krishnan, Secretary, MeitY	Importance of Modules in GOI's vision for Development of ESDM Ecosystem
15:10 - 15:20	**Keynote Address** Sh. Ashwini Vaishnaw, Hon'ble Minister, Railways, I&B, Electronics & IT	GoI's Vision for Semiconductor Sector Expansion
15:20 - 15:40	**Market Overview** Sh. Tarun Pathak, Research Director, Counterpoint Research	Overview of Global/Indian Module Market, Major Players and End Users
15:40 - 16:00	**Technical Overview** Sh. Sanjay Razda, Senior Director,Qualcomm	Technical Overview of Modules Including Skill Requirements
16:00 - 16:20	**Imperatives for a Local Module Ecosystem** Sh. Konark Bhandari, Head - Technology & Society, Carnegie India	Risks and Critical Requirement of Indigenous Module Ecosystem in India
16:20 - 17:00	**Panel Discussion: Support Required for a Robust Module Ecosystem** **Moderator: ISM** **Panelists**: Cavli Chakra MoMagic Melange Teksun	Panel discussion on Challenges and Support Required by Module Comp
Session 3 : Keynote Presentations - Creating a Vibrant Semiconductor Ecosystem in India | Banquet Hall - Room 8 [Level 2]		
14:30 - 14:35	**Welcome Remarks by Session Chair**	Bettina Weiss, Chief of Staff & Corporate Strategy, SEMI
14:35 - 14:45		Akash Tripathi, CEO, India Semiconductor Mission (ISM)
14:45 - 14:55		Takehiko Matsuo, Vice-Minister for International Affairs, Ministry of Economy, Trade and Industry (METI) Japan
14:55 - 15:05		Robert Garverick, DAS, Deputy Assistant Secretary of State for Trade Policy and Negotiations, U.S. Department of State
15:05 - 15:15		Srinivas Satya, Chief Supply Chain Officer, Tata Electronics

Time (Hrs)	Session Name & Description	Participants/Speakers
15:15 - 15:25		Scott DeBoer, Executive Vice President of Technology and Products at Micron Technology, Micron
15:25 - 15:35		Anirudh Devgan, CEO, Cadence
15:35 - 15:45		Hidetoshi Shibata, CEO, Renesas
15:45 - 15:55		Dr. Mukesh Khare, Vice President of IBM Research, IBM
15:55 - 16:05		Gregory Smith, CEO, Teradyne
16:05 - 16:15		Satheesh Kuppurao, Group Vice President Business Development & Growth Semiconductor Products Group, Applied Materials
16:15 - 16:25		Kurt Sievers, CEO, NXP
16:25 - 16:35		Rutger Wijburg, CEO, Infineon
16:35 - 16:45		Luc Van den hove, CEO, imec
16:45 - 16:55		Bob Pragada, CEO, Jacobs
16:55 - 17:05		Yoshiaki Yoshida, Director, Chairperson of the Board, Advantest
17:05 - 17:15		Tony Kawai, President & CEO, Tokyo Electron
17:15 - 17:25		Sandeep Kumar, CEO, SiLT
17:30 - 18:15	**Round Table Discussion: Perspectives on Lessons Learned from Greenfield Projects in other Regions**	**Moderator** Luc Van den hove, President and CEO, imec **Panelists**: - Michael Lesniak, Vice President Hi-Tech Sector, Aquatech - Anthony Renzulli, Associate Partner, ASG - Dr. Srikanth (Sri) Kommu, Executive Vice President (EVP) and Chief Operating Officer (COO) , Brewer Science - Frank Lorenzetto, Managing Director, Exyte - Raghu Panicker, CEO, Kaynes Semicon - Manjunath Jyothinagar, Managing Director, UHP/KAS Technologies
18:15 - 18:20	**Closing Remarks by Session Chair**	Bettina Weiss, Chief of Staff & Corporate Strategy, SEMI

Time (Hrs)	Session Name & Description	Participants/Speakers
Session 4: Advanced Packaging - Advanced Packaging & Heterogeneous Integration - India's Roadmap to the Next Frontier | Hall 2 - Room 2 [Level 2]		
14:55 - 15:00	**Welcome Remarks by Session Chair**	Mark da Silva, Ph.D., Sr. Director, Smart Manufacturing Initiative - SEMI Smart Manufacturing / Advanced Packaging & Heterogeneous Integration (APHI) Community, SEMI
15:00 - 15:15	**Process Control Challenges for Advanced Packaging**	Dr. Lena Nicolaides, Vice president and General Manager of Patterned Wafer Inspection Products, KLA
15:15 - 15:30	**The Fourth Industrial Revolution (4IR) and Its Impacts**	Maitreyee Mahajani , SVP Fab Operations, Western Digital
15:30 - 15:45	**Materials Engineering Innovations to Address Next-Generation Electronics Packaging Challenges**	Dr. Sundar Ramamurthy, Group Vice President, General Manager, Epitaxy, Packaging and ICAPS, Semiconductor Products Group, Applied Materials, Inc.
15:45 - 16:00	**Global Trends and Challenges in Semiconductor Packaging**	Dr. Pavel Seroglazov, Manager of Strategic Partnerships, BESI
16:00 - 16:15	**Future of AI Hardware Enabled by Advanced Packaging: How the Burgeoning India Ecosystem Help Lead This Drive**	Dr Raja Swaminathan, CVP of Packaging, AMD
16:15 - 16:20	**Closing Remarks by Session Chair**	Mark da Silva, Ph.D., Sr. Director, Smart Manufacturing Initiative - SEMI Smart Manufacturing / Advanced Packaging & Heterogeneous Integration (APHI) Community, SEMI
Time (Hrs)	Session Name & Description	Participants/Speakers
Session 5: Electronics Systems Development and Application Forum | Hall 2 - Room 2 [Level 2]		
16:25 - 16:30	**Opening Remarks by Session Chair**	
16:30 - 16:45	**Keynote: Memory at the core of the AI Momentum** **– Unleashing the AI Revolution through Pioneering Innovations in Memory and Storage Systems**	Subhash Chintamaneni, Senior Director,ASIC Development Engineering, Micron Technology
16:45 - 17:00	**3D-IC Technology: Signoff Challenges & Solutions**	Arvind Veeravalli, Senior Software Architect, Cadence Design Systems
17:00 - 17:15	**Static Signoff and Hardware Security**	Ashish Hari, Country Head - India R&D, Real Intent

Time (Hrs)	Session Name & Description	Participants/Speakers
17:15 - 17:45	**Panel Discussion: EDA Responds to the Challenges of Advanced Manufacturing Technologies**	**Moderator:** Nitin Dahad, Editor-in-Chief, EE Times **Panelists**: - Dave Kelf, CEO, Breker Verification System - Roopashree HM, Global Director - EDA, Texas Instruments - Aveek Sarkar, Vice President, Synopsys
17:45 - 17:50	**Closing Remarks by Session Chair**	
18:30 PM - 21:00 PM	SEMICON India Networking Dinner	

Day 2 | Thursday, 12 Sept 2024		
Session 1 : Workforce Development | Hall 2 - Room 2 [Level 2]		
09:55 - 10:00	Welcome Remarks by Session Chair	Shari Liss, VP - Global Workforce Development & Initiatives, SEMI
10:00 - 10:15		Roopa Purushothaman, Chief Economist and Head of Policy Advocacy, Tata Electronics
10:15 - 10:30	Collaborative Workforce Development to address India's Semiconductor Manufacturing Requirements	Dr. Suraj Rengarajan, Managing Director & Head Semiconductor Products Group (SPG), Applied Materials India
10:30 - 10:45		Prof T. G. Sitharam, Chairperson, All India Council for Technical Education (AICTE)
10:45 - 11:00	Semiconductor Manufacturing and Industry 4.0 Ready Workforce and Talent Pipeline Development	Vishwanath Ramaswamy, Vice President, Micron
11:00 - 11:15		Dr Abhilasha Gaur, CEO, Electronics Sector Skill Council of India (ESSCI)
11:15 - 11:25	SEMI Workforce Development (WFD) Programs Overview	Shari Liss, VP - Global Workforce Development & Initiatives, SEMI
11:25 - 11:30	Closing Remarks by Session Chair	Shari Liss, VP - Global Workforce Development & Initiatives, SEMI
Session 2 : Smart MedTech | Hall 2 - Room 3 [Level 2]		
09:30	Keynote session Chair-	Dr Nandini Tandon, Venture Capitalist, Silicon Valley; Co-founder, Indus Setu Foundation
09:30 - 09:35	Opening Welcome	Vinod Dham, Father of the Pentium Chip and Ajit Manocha, President and CEO, SEMI
09:35 - 09:40	Opening Speaker: Accelerating Global Health Equity: FDA's Vision	Dr. Robert Califf, Commissioner of Food and Drugs, Food and Drugs Administration, Government of the United States of America

Time (Hrs)	Session Name & Description	Participants/Speakers
09:40 - 09:50	Keynote Speaker: India's Blueprint for the Future of AI and Semiconductor Enabled Healthcare	S Krishnan, Secretary, Ministry of Electronics and Information Technology, Government of India
09:50 - 10:10	Interdisciplinary Fireside Chat: Harnessing Public-Private Partnership for Tech-Enabled Health for AI	-Dr. Rakesh Bhatnagar, National Science Chair, Jawaharlal Nehru University -Mona Khandhar, Principal Secretary, Science and Technology, Government of Gujarat -Anshuman Tripathi, Member of the National Security Advisory Board -Dr. Chang Yee-Shyi, Executive Director, Taiwan Baojia Health Management International Holdings
	Plenary Panel Chair-	Dr. Anurag Mairal, Adjunct Professor of Medicine and the Director, Global Outreach Programs at Stanford Byers Center for Biodesign, Stanford University
10:10 - 10:55	Panel Debate: Convergence of MedTech, Semiconductors and AI for Transforming Global Healthcare	-Mehnaz Ansari, Senior Regional Representative, South Asia, USTDA -Dr. Stephan Guttowski, Managing Director, Research Fab Microelectronics Germany (FMD) -Pankaj Mohindroo, Founder and President, Indian Cellular and Electronics Association (ICEA)
10:55 - 11:25	Roundtable Discussion: Innovation, Investment, and Implementation	**Moderator:** -Shashi Shekhar Vempati, Co-founder, DeepTech for Bharat Foundation **Panelists:** -Dr. Ayesha Chaudhary, India Director, WomenLift Health -Neeraj Jain, Director for Growth, PATH - Asia, the Middle East and Europe (AMEE) -Sunil Singh, Founder & CEO, UnivLabs Technologies Private Limited -Venkatakrishnan S, CTO & Head of R&D, Forus Health
11:25 - 11:30	**Next Steps and Wrap up**	Dr. Nandini Tandon, Venture Capitalist in Silicon Valley and Co-Founder, IndusSetu Global Foundation
	Closing Remarks	

Time (Hrs)	Session Name & Description	Participants/Speakers
Session 3 : Keynote Presentations - Global Market, Local Execution - The Benefits of Cross-Regional Partnerships | Banquet Hall - Room 8 [Level 2]		
11:00 - 11:05	**Welcome Remarks by Session Chair**	Ashok Chandak, President, India Electronics and Semiconductor Association (IESA)
11:05 - 11:15		Pankaj Kukkal, Executive Vice President, MCU/MPU Engineering, NXP
11:35 - 11:45		Jayant Patil, L & T
11:45 - 11:55		KC Ang, GlobalFoundries
11:55 - 12:05		Surésh Rajaraman, Executive Vice President & Head of Thin Film, Merck Electronics
12:05 - 12:15		Rangesh Raghavan, Corporate Vice President and General Manager, Lam Research
12:15 - 12:25		Santosh Kumar, Texas Instruments
12:15 - 13:00	**Lunch Break**	
		Moderator: Sanjay Gupta, Global Head of Engineering, L&T Semiconductors; IESA Board Advisor
13:00 - 13:10		Dr V Veerappan, President & Co Founder, Tessolve
13:10 - 13:20		Navin Bishnoi, Associate Vice President and India Country Manager, Marvell India Pvt Ltd
13:20 - 13:30		Stephan Guttowski, Managing Director, Fraunhofer Institute
13:30 - 13:40		Shoji Otaka, Executive Officer,Division Manager of Corp Planning Div, TOK
13:40 - 13:50		Sambit Sahu, Ola Krutrim
13:50 - 14:00	Closing remarks by moderators	
14:00 - 16:15	**State session, Moderator:** Col. Anurag Awasthi, Vice President, IESA	**State Participation:** Andhra Pradesh, Assam, Gujarat, Karnataka, Madhya Pradesh, Odisha, Tamil Nadu, Telangana, Uttar Pradesh
Session 4 : Flexible Hybrid Electronics | Hall 2 - Room 2 [Level 2]		
11:25 - 11:30	**Welcome Remarks by Session Chair**	Dr. Gity Samadi, Sr. Director - R&D, SEMI
11:30 - 11:45	**Keynote Presentation**	Dr. Ashiwini Aggarwal, Chair- Semiconductor Skills Committee,

		Electronics Sector Skill Council of India
Time (Hrs)	**Session Name & Description**	**Participants/Speakers**
11:45 - 12:00	**Flexible and Hybrid Electronics - Challenges and Opportunities in India**	Dr. Siddhartha Panda, Professor - Department of Chemical Engineering, NCFlexE, IIT Kanpur
12:00 - 12:15	**Mass production with ultrahigh-precision inkjet printing: NeuralJet™ Technology**	Masaki Sugimoto, Co Founder and Senior Vice President, Elephantech
12:15 - 12:50	**Advancing Manufacturing through Design and Innovation in Flexible Hybrid Electronics**	**Moderator:** **Dr. Sudheer Kumar, COO, NCFlexE, IIT Kanpur** **Panelists:** - S. N. Venkataraman, CEO, ITC Packaging & Business - Masaki Sugimoto, Co Founder and Senior Vice President, Elephantech - Asha Nangia, Scientist G and Group Coordinator, Ministry of Electronics & Information Technology (MEITY) - Dr. Rajesh Kulkarni, Founder and Director, Keetronics India - Dr. Ram Prasad Gandhiraman, Founder & CEO, Space Foundry Inc
12:50 - 12:55	**Closing Remarks by Session Chair**	Dr. Gity Samadi, Sr. Director - R&D, SEMI
Session 5 : Supply Chain Management | Hall 2 - Room 2 [Level 2]		
13:55 - 14:00	**Welcome Remarks by Session Chair**	Bettina Weiss, Chief of Staff & Corporate Strategy, SEMI
14:00 - 14:40	**Fireside Chat**	**Moderator:** Bettina Weiss, Chief of Staff & Corporate Strategy, SEMI **Panelists:** - Srinivas Satya, Head Supply Chain & Component Business Unit, Tata Electronics - Boris Metodiev, Director, Manufacturing Analysis, TechInsights
14:40 - 14:55	**Global Supply Chain Environment - Rethinking the Industry**	Troy Mills, Vice President, Global Supply Chain Operations, Applied Materials, Inc.
14:55 - 15:10		Peter Holland, Corporate VP - Supply Chain, Lam Research
15:10 - 15:15	**Closing Remarks by Session Chair**	Bettina Weiss, Chief of Staff & Corporate Strategy, SEMI
Session 6 : Sustainability | Hall 2 - Room 2 [Level 2]		

15:25 - 15:30	**Welcome Remarks by Session Chair**	Mousumi Bhat, VP - SEMI Global Sustainability Programs, SEMI

Time (Hrs)	Session Name & Description	Participants/Speakers
15:30 - 15:45	**Circularity and Additive Technology**	Dr Sandip Chatterjee, Former Senior Director & Group Coordinator, Ministry of Electronics and Information Technology (MEITY)
15:45 - 16:00	**The Sustainability Inflection**	Dr. Nasreen Chopra, Vice President, Sustainability Systems, Semiconductor Products Group, Applied Materials, Inc.
16:00 - 16:15	**Materials Intelligence: Enabling Sustainable Semiconductor Supply Chains for India**	Surésh Rajaraman, Executive Vice President & Head of Thin Film, Merck Electronics
16:15 - 16:45	**Panel Discusssion: Innovation and Sustainability**	**Moderator:** Mousumi Bhat, VP - SEMI Global Sustainability Programs, SEMI **Panelists:** - Karthik Ganesan, Fellow and Director - Research Coordination, Council on Energy, Environment and Water (CEEW) - Dr. Cameron Lippert, Co-Founder and Chief Innovation Officer, ElectraMet - Michael Lesniak, VP Partnerships, Aquatech
16:45 - 17:00		Raghu Kiran Ganti, Distinguished Engineer,Hybrid Cloud and AI Platform, IBM Research
17:00 - 17:05	**Closing Remarks by Session Chair**	Mousumi Bhat, VP - SEMI Global Sustainability Programs, SEMI

Day 3 | Friday, 13 Sept 2024		
Session 1 : Package Manufacturing Bootcamp by Micron | Hall 2 - Room 2 [Level 2]		
10:00 AM - 12:00 PM	Instructor	Dr. Gokul Kumar
	SYSTEM IN PACKAGE FUNDAMENTALS	Types of semiconductor packages & requirements, Package and Product Roadmap for Advanced Memory and AI/ML applications, High Bandwidth Memories, New Product Introduction (NPI) business process, Electronic Design Automation (EDA) for packages, Advanced Codesign &

		Simulation techniques for future System optimization
	PACKAGE MANUFACTURING PROCESSES	Packaging Assembly Technology, Wafer Thinning, Dicing, Die Attach, Wire bonding, Flip Chip process, Flux Cleaning, Underfill, Encapsulation, Laser Marking, Solder Ball Attach, Reflow, Singulation, IC Packaging Toolsets & equipment operation, clean room operations.
	SEMICONDUCTOR PACKAGE MATERIALS AND QUALIFICATION	Reliability testing & qualification- MST/MSL, TC/TS, HAST & uHAST, Mold Compounds (Moldability), Underfill Materials, Die Attach Adhesives & Films, Substrate Technology, Bonding Wire, Solder & Dielectric materials.
12:00 PM - 13:00 PM	Sand to Silicon: An Overview of Semiconductor Journey - By IESA	
13:45 PM - 14:45 PM	From Sand to Electronic Systems: An Overview of Semiconductor Journey - By IESA	
14:45 PM - 16:45 PM	An Introduction to Semiconductor Fabrication - By IESA	

Parallel Sessions | Day 1

Workshop on Development of Indigenous Wireless Module (02:30 PM – 04:30 PM)

Time (Hrs)	Agenda	Description	Speakers
02:30 PM – 02:35 PM	Opening Remarks	Welcome attendees and introduction to workshop	Sh. Akash Tripathi, CEO, India Semiconductor Mission
02:35 PM – 02:40 PM	Address	Importance of Modules in GOI's vision for development of ESDM ecosystem	Sh. S. Krishnan, Secretary MeitY
02:40 PM – 02:50 PM	Keynote Address	GoI's vision for Semiconductor sector expansion	Sh. Ashwini Vaishnaw, Hon'ble Minister Railways I&B Electronics & IT
02:50 PM – 03:10 PM	Market Overview	Overview of global/ Indian module market, major players, end users	Sh. Tarun Pathak, Research Director Counterpoint Research
03:10 PM – 03:30 PM	Technical Overview	Technical overview of modules including skill requirements	Sh. Debesh Kumar Sahu, Senior Director Qualcomm

03:30 PM – 03:50 PM	Imperatives for a Local Module Ecosystem	Risks and critical requirement of indigenous module ecosystem in India	Sh. Konark Bhandari, Head Technology & Society, Carnegie India
03:50 PM – 04:30 PM	Panel Discussion: Support required for a Robust Module Ecosystem	Panel discussion on challenges and support required by module companies	Moderator : ISM Panelists : Cavli Chakra MoMagic Melange Teksun

Parallel Sessions | Day 2

Holistic Semiconductor Ecosystem Development through Cooperative Federalism (02:30 PM – 04:00 PM)

Panel Discussion with State Government: "Holistic Semiconductor Ecosystem Development through Cooperative Federalism" Moderator: Col. Anurag Awasthi, Vice President, IESA	States for Panel Discussion : Uttar Pradesh Gujarat Assam Karnataka Tamil Nadu Telangana Andhra Pradesh Odisha Madhya Pradesh

MeitY-Industry-Academia (MIA) Workshop (02:00 PM - 06:00 PM)

Inaugural Session (02:00 PM – 03:00 PM)

Keynote 1: Building the Nation from Ground Up	Shri S Krishnan, Secretary, MeitY
Keynote 2: Grand challenge & Opportunity for ICCs	Dr. Randhir Thakur, CEO, Tata Electronics
Keynote 3: Grand Challenge & Opportunity for India	Vinay Shenoy, India Head, Infineon
Keynote 4: Vision for India to be a Global Hub	Prof. Rao Tummala, Emeritus Professor & Advisor to MeitY

12 Industry Co-Development Center Proposals (03:00 PM – 04:10 PM)

Industries	Faculty Leads	Co-Leads	Industry Leads
1 - System Design & Architecture	Prof. Binod Kumar (IITJ)	Prof. Nanditha Rao, (IIITB)	
2A - Devices – CMOS	Prof. Nihar Mohapatra (IITGN)	Prof. Abhisek Dixit (IITD)	
2B - Devices – Power	Prof. Akshay K (IITBBS)	Prof. Ankush Bag (IITG)	
3 - Interconnecting Substrates	Prof. Pradeep Dixit (IITB)	Prof. Deepak Arora (IITJ)	
4 - Co-Packaged Optics	Prof. Naresh Emani (IITH)	Prof. Sudharsanan (IITM)	
5 - Predictive Modelling & Design	Prof. Tarun Agarwal (IITGN)	Prof. Somnath Roy (IITKGP)	
6 - 6G Integrated Systems	Prof. Mrinal Mandal (IITKGP)	Prof. Siddhartha D (IITB)	

7 - Integrated Sensors & MEMS	Prof. Bhaskar Mitra (IITD)	Prof. Venkatesh (BITS Pilani)	
8 - Materials – Device & Packaging	Prof. Bhagwati Prasad (IISc)	Prof. Praveen R (IISc)	
9 - IC & Board Assembly and Reliability	Prof. Nilesh Badwe (IITK)	Prof. Shiv Govind (IITH)	
10 - Power Electronics	Prof. Shiladri Chakraborty (IITB)	Prof. Apurv Kumar (IITR)	
11 - Thermal Management	Prof. Anandaroop B (IITKGP)	Prof. Amrit Ambirajan (IISc)	Shailesh Joshi, Toyota USA
12 - System Level Electrical Test	Prof. Jaynarayan Tudu (IITTP)	Prof. Satyadev A, (IIT Jammu)	
Directors Session (04:10 PM – 04:55 PM)			
Topics		Prof. Rao Tummala, Emeritus Professor & Advisor	
Director's Keynote		Prof. V Ramgopal, VC, BITS Pilani	
Directors Panel Session Prof. V Ramgopal Rao, VC, BITS Pilani		Prof. Shireesh Kedare (IITB) Prof. B S Murty (IITH) Prof. Virendra Kumar Tewari (IITKGP) Dr. K Satyanarayana (IITTP) Prof. Rajat Moona (IITGN) Prof. Rajeev Ahuja (IITRPR) Prof. Shreepad Karmalkar (IITBBS) Prof. Manindra Agrawal (IITK)	
Industry Panel Session (04:55 PM – 05:55 PM)			
Industry Panel Session Veerappan, Chairman, Tessolve		• Arun Chandrasekhar (Intel) • Anand Ramamoorthy (Micron) • Randhir Thakur (Tata) • Santhosh Kumar (TI) • Vinay Shenoy (Infineon) • Raghu Panicker (Kaynes) • Paresh Bharkhada (Teradyne) • Jaya Jagadish (AMD) • Shital Joshi (Ansys) • Suraj Rengarajan (AMAT) • Navin Goudar (MKS) • Sudhir Pillai (Corning) • Jitendra Cheddah (GF) • Ravi Bhatkal (MacDermid) • Arvind Tripathi (Mitsui) • Sumit Goswami (Qualcomm) • Abe Hidenori (Resonac) • Vivek Sharma (ST) • BRR Rao (Techsol) • Supria Dhanda (Western Digital) • Navin Bishnoi (Marvell) • Vivek Raghuraman (Mixxtech) • Rohin Yeluripati (Light Speed)	

	• Hitesh Garg (NXP) • S Sunil Kumar (Henkel) • Shetal Mehta (Suchi Semicon) • Krishna Thakur (LTSCT)